

Notification Number:	20260707002.0	Notification Issued	July 16, 2026
Datasheet for LMP860x and LMP860x-Q1			

Change Type(s)	Data Sheet/Electrical Specification
ZVEI ID(s)	SEM-DS-02

Notification Details

Description of Change:
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  LMP8601, LMP8602, LMP8603 SLVSJ15 – JUNE 2026 The LMP860x device is moved from SNOSAR2 "I" revision data sheet to the current standalone datasheet. The changes from the SNOSAR2 "I" revision to this document are as follows: • Updated the numbering format for tables, figures, and cross-references throughout the document. • Deleted ESD Classification from the Features section. • Updated applications with links in Applications section. • Added Abs Max differential input voltage specification in Absolute Maximum Ratings table. • Deleted Machine Model ESD rating from ESD Ratings table. • Updated Thermal Information for D (SOIC) package in Thermal Information table. • Changed common-mode input impedance for SOIC (D) package in Electrical Characteristics: $V_s = 3.3V$ table. • Changed differential-mode input impedance for SOIC (D) package in Electrical Characteristics: $V_s = 3.3V$ table. • Changed typical input bias current specification in Electrical Characteristics: $V_s = 3.3V$ table. • Changed common-mode input impedance for SOIC (D) package in Electrical Characteristics: $V_s = 5V$ table. • Changed differential-mode input impedance for SOIC (D) package in Electrical Characteristics: $V_s = 5V$ table. • Changed typical input bias current specification in Electrical Characteristics: $V_s = 5V$ table. • Changed Input Bias Current Over Temperature (A2 pin) at $V_s = 5V$ curve in Typical Characteristics. • Added Vos Distribution at $V_s = 3.3V$ and $V_s = 5V$ plots for SOIC (D) package in Typical Characteristics. • Added Vos drift vs Temperature plots for SOIC (D) package in Typical Characteristics. • Added Gain Error Distribution plots for SOIC (D) package in Typical Characteristics. • Added Gain drift vs Temperature plots for SOIC (D) package in Typical Characteristics. • Added CMMR Distribution plots for SOIC (D) package in Typical Characteristics. • Added CMRR drift vs Temperature plots for SOIC (D) package in Typical Characteristics. • Added the Related Documentation section.

Changes from Revision H (April 2016) to Revision I (June 2026)
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• Moved the commercial device to a standalone data sheet (SLVSJ15).....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Deleted device Machine Model ESD Classification from the <i>Features</i> Section	1
• Added Functional Safety-Capable document to the <i>Features</i> Section	1
• Updated applications with links.....	1
• Added Abs Max differential input voltage specification per TI standard	3
• Deleted Machine Model ESD rating.....	3
• Updated thermal Information for D (SOIC) package.....	3
• Changed common-mode input impedance values for SOIC (D) package.....	4
• Changed differential-mode input impedance values for SOIC (D) package.....	4
• Changed typical input bias current specification.....	4
• Changed Common-mode input impedance values for SOIC(D) package.....	6
• Changed differential-mode input impedance values for SOIC (D) package.....	6
• Changed typical input bias current specification.....	6
• Updated Input Bias Current Over Temperature (A2 pin) at VS = 5V curves.....	9
• Added Vos Distribution at Vs =3.3V and Vs =5V plots for SOIC (D) package	9
• Added Vos drift vs Temperature plots for SOIC (D) package.....	9
• Added Gain Error Distribution plots for SOIC (D) package	9
• Added Gain drift vs Temperature plots for SOIC (D) package	9
• Added CMMR Distribution plots for SOIC (D) package	9
• Added CMRR drift vs Temperature plots for SOIC (D) package	9
• Added the <i>Related Documentation</i> section.....	34

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMP860x	SNOSAR2H	SLVSJ15
LMP860x-Q1	SNOSAR2H	SNOSAR2I

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMP8601>

<http://www.ti.com/product/LMP8601-Q1>

Reason for Change:	To accurately reflect device characteristics
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	No anticipated impact
Changes to product identification resulting from this PCN:	None

Products Affected:		
LMP8602MMX/NOPB	LMP8602MMX/NOPB.A	LMP8603MMX/NOPB
LMP8603MMX/NOPB.A	LMP8601EDRQ1	LMP8601EDRQ1.A
LMP8602QMMX/NOPB	LMP8602QMMX/NOPB.A	LMP8603QMMX/NOPB
LMP8603QMMX/NOPB.A		

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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